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Abstract of the Disclosure

A socket for mounting a processor and/or a board has a substrate with a built in socket. The socket has conductive, elastically deformable terminals. The socket
5 may be mounted to a processor and a board without using conventional surface mount technology, instead providing a mechanical contact mechanism between the socket and the board or processor. An adhesive layer may also be used to connect the socket to a processor and/or a board.

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